


























Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Layer 1	Copper	0.67mil	
5		Dielectric1	1080HR RC68	2.90mil	4.02
6		Layer 2P	Copper	1.20mil	
7		Dielectric6	1080HR RC68	4.75mil	4.34
8		Layer 3	Copper	1.20mil	
9		Dielectric2	1080HR RC68	4.75mil	4.02
10		Layer 4	Copper	1.20mil	
11		Dielectric3	1080HR	4.75mil	4.34
12		Layer 5P	Copper	1.20mil	
13		Dielectric9	1080HR	14.48mil	4.56
14		Layer 6P	Copper	1.20mil	
15		Dielectric7	1080HR	4.75mil	4.34
16		Layer 7	Copper	1.20mil	
17		Dielectric4	1080HR RC68	4.75mil	4.02
18		Layer 8	Copper	1.20mil	
19		Dielectric5	1080HR RC68	4.75mil	4.34
20		Layer 9P	Copper	1.20mil	
21		Dielectric8	1080HR RC68	2.90mil	4.02
22		Layer 10	Copper	0.67mil	
23		Bottom Solder	Solder Resist	0.40mil	3.5
24		Bottom Overlay			
25		Bottom Paste			

Height : 60.52mil